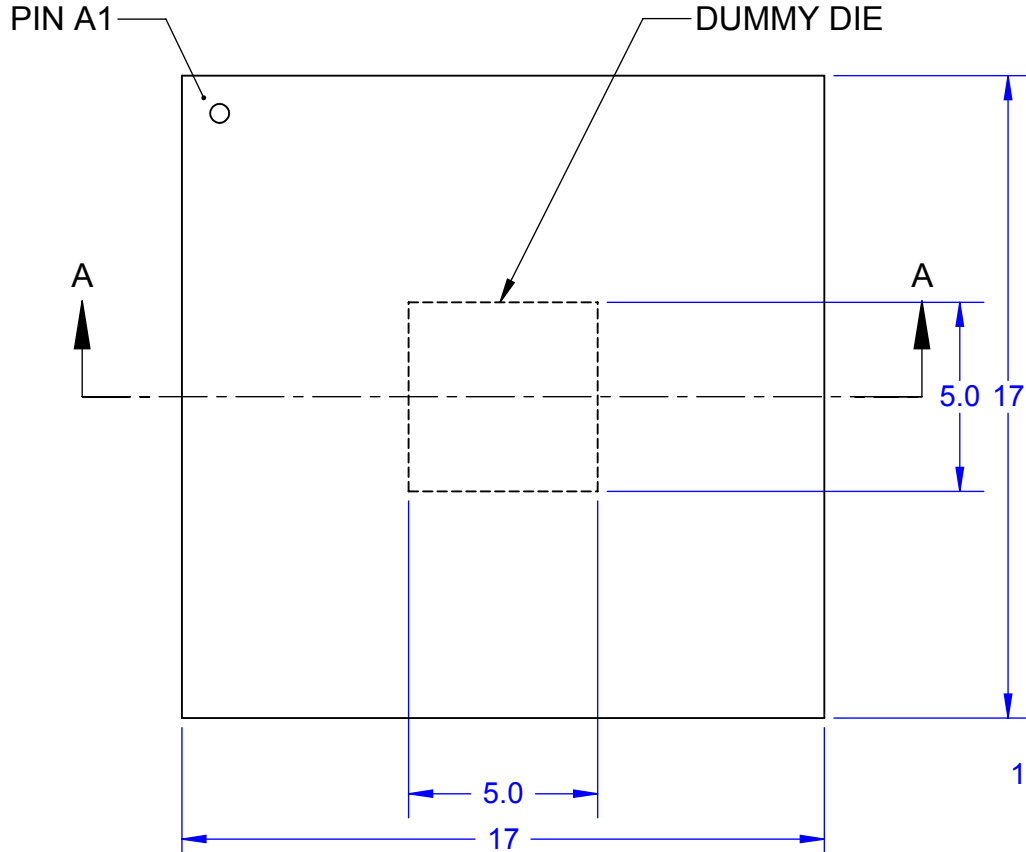
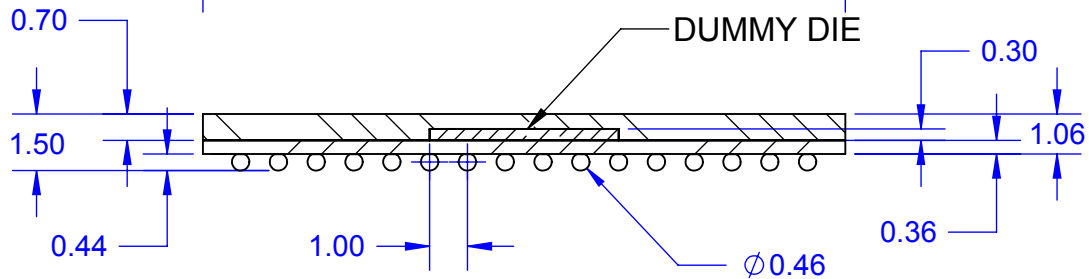
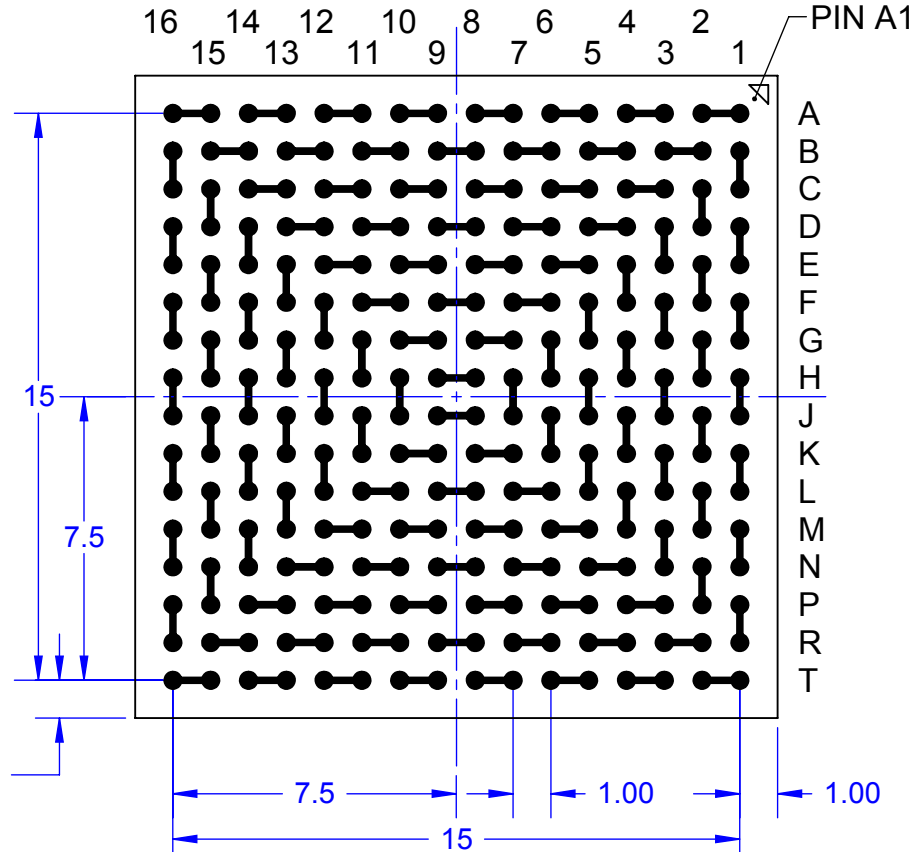


**TOP VIEW**



**BALL VIEW**



**SECTION A-A**

Notes: (Unless Otherwise Specified).

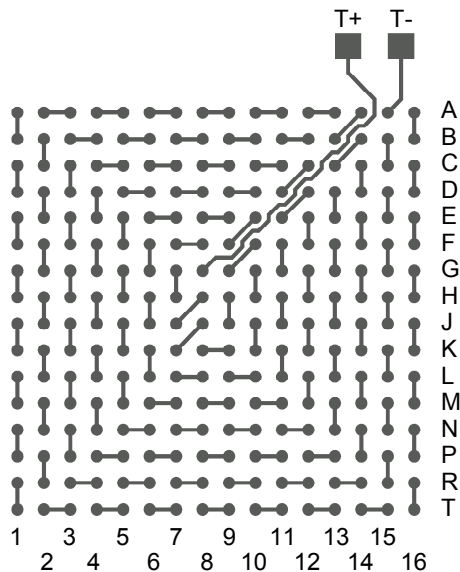
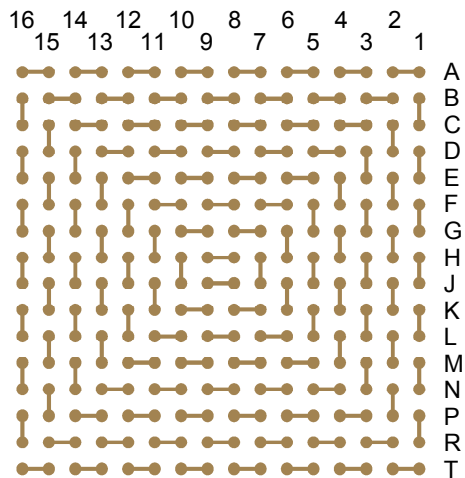
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.46mm (18 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.40mm (15.7 MIL).
- 5) PAD Cu DIAMETER: 0.46mm (18 MIL).
- 6) SUBSTRATE MATERIAL: BT RESIN.
- 7) DUMMY DIE OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

**PART NUMBER TABLE**

PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA256T1.0C-DC169D	Sn96.5/Ag3.0/Cu0.5	SAC35	YES	YES
BGA256T1.0-DC169D	Sn63/Pb37	Sn63	NO	YES

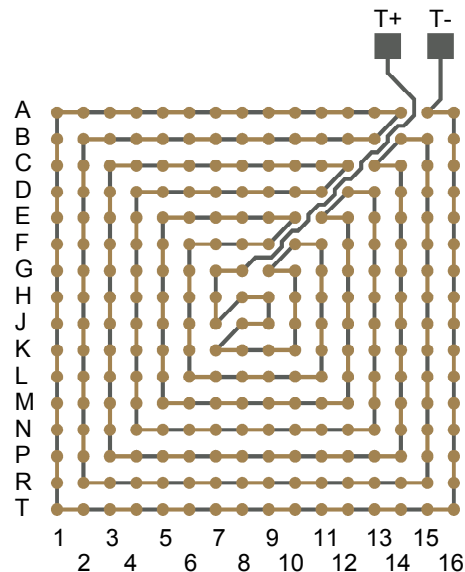
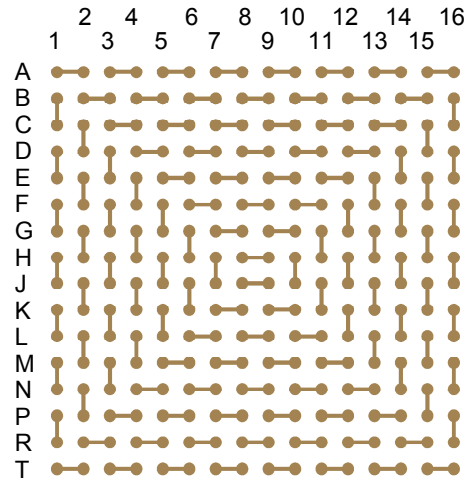
APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T.Au	6/23/13				
ENG M. Hart	6/23/13	TITLE BGA256T1.0C-DC169D DAISY CHAIN DUMMY			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		5:1	A	511690	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

### BALL VIEW



### TEST VEHICLE BOARD

### BOTTOM SIDE (TOP X-RAY VIEW)



### AFTER MOUNTING

**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: 0.46mm (18 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.152mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.40mm (15.7 MIL).

<b>TopLine®</b>			
TITLE		BGA256T1.0C-DC169D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3.5:1	A	511690	A
DO NOT SCALE DRAWING			SHEET 2 OF 2